



TGR 4000

Known as TIC 4000
November 2018

PRODUCT DESCRIPTION

High Performance Thermal Interface Compound for Copper-Based Heat Sinks.

Technology	Silicone
Appearance	Gray
Application	Thermal management, Thermally conductive adhesive
Operating Temperature	150 °C

FEATURES AND BENEFITS

- Thermal Conductivity: 4.0 W/m-K
- Excellent thermal performance: 0.19°C/W @ 50psi

TGR 4000 is a thermally conductive grease compound designed for use as a thermal interface material between a computer processor and a copper-based heat sink. Other high watt density applications will benefit from the extremely low thermal impedance of TGR 4000.

The TGR 4000 compound wets-out the thermal interface surfaces and flows to produce the lowest thermal impedance. The compound requires pressure of the assembly to cause flow. TGR 4000 compound will not drip.

For a typical 0.5" x 0.5" application at 0.005" thick, Bergquist estimates approximately 0.02 ml (cc) of TGR 4000.

Although Henkel estimates a 0.02 ml (cc) volumetric requirement for a 0.5" x 0.5" component interface, dispensed at a thickness of 0.005", Henkel also recognizes that an optimized application would utilize the minimum volume of TGR 4000 material necessary to ensure complete wet-out of both mechanical interfaces.

TYPICAL APPLICATIONS

- High performance computer processors (traditional screw fastening or clamping methods will provide adequate force to optimize the thermal performance of TGR 4000)
- High watt density applications where the lowest thermal resistance interface is required

TYPICAL PROPERTIES

Physical Properties

Density, ASTM D792, g/cc 4.0

Electrical Properties

Electrical Resistivity, ASTM D257, ohm-meter N/A
The compound contains an electrically conductive filler surrounded by electrically non-conductive resin

Thermal Properties

Thermal Conductivity , ASTM D5470, W/(m-K) 4.0

Thermal Performance vs. Pressure

TO-220 Thermal Performance, °C/W

@ 10 psi	0.21
@ 25 psi	0.2
@ 50 psi	0.19
@ 100 psi	0.19
@ 200 psi	0.18

TO-220 performance data is provided as a reference to compare material thermal performance

GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

Directions for use

Application Methods

1. Pre-clean heat sink and component interface with isopropyl alcohol prior to assembly or repair. Ensure heat sink is dry before applying TGR 4000
2. Dispense TGR 4000 compound onto the processor or heat sink surface like thermal grease
3. Assemble the processor and heat sink with spring clips or constant pressure fasteners

Not for product specifications

The technical data contained herein are intended as reference only. Please contact HITEK Electronic Materials for assistance and recommendations on specifications for this product.



Conversions

$(^{\circ}\text{C} \times 1.8) + 32 = ^{\circ}\text{F}$
 $\text{kV/mm} \times 25.4 = \text{V/mil}$
 $\text{mm} / 25.4 = \text{inches}$
 $\text{N} \times 0.225 = \text{lb}$
 $\text{N/mm} \times 5.71 = \text{lb/in}$
 $\text{psi} \times 145 = \text{N/mm}^2$
 $\text{MPa} = \text{N/mm}^2$
 $\text{N}\cdot\text{m} \times 8.851 = \text{lb}\cdot\text{in}$
 $\text{N}\cdot\text{m} \times 0.738 = \text{lb}\cdot\text{ft}$
 $\text{N}\cdot\text{mm} \times 0.142 = \text{oz}\cdot\text{in}$
 $\text{mPa}\cdot\text{s} = \text{cP}$

Disclaimer**Note:**

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

In case products are delivered by Henkel Belgium NV, Henkel Electronic Materials NV, Henkel Nederland BV, Henkel Technologies France SAS and Henkel France SA please additionally note the following:

In case Henkel would be nevertheless held liable, on whatever legal ground, Henkel's liability will in no event exceed the amount of the concerned delivery.

In case products are delivered by Henkel Colombiana, S.A.S. the following disclaimer is applicable:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

In case products are delivered by Henkel Corporation, Resin Technology Group, Inc., or Henkel Canada Corporation, the following disclaimer is applicable:

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

Trademark usage: [Except as otherwise noted] All trademarks in this document are trademarks and/or registered trademarks of Henkel and its affiliates in the U.S. and elsewhere.

Reference 1

<p>Supplied by: www.hitek-ltd.co.uk +44 (0)1724 851678</p>		<p>HITEK ELECTRONIC MATERIALS LTD</p>
---	---	---

Americas
+1.888.943.6535

Europe
+32.1457.5611

Asia
+86.21.3898.4800

For the most direct access to local sales and technical support visit: www.henkel.com